

AIM (Advanced Inspection & Metrology)

TEL's Advanced Inspection & Metrology (AIM) Department provides advanced inspection tools manufactured by top suppliers from around the world. The semiconductor industry's most innovative defect inspection system is the e-beam.

The tool provides the best sensitivity and imaging available for improving yields and enabling next generation technologies.

eScan[®] 315/380 Hermes Microvision, Inc.

Electron-Beam Defect Inspection System



Applications

- Gate/Junction leak
- Open contact
- Line short / Footing / Protrusion

Features

- Low landing energy inspection
- High resolution inspection
- High resolution review
- BSE review

The eScan 315/380, a collaboration between TEL and Hermes Microvision, Inc., is the most advanced e-beam defect inspection tool available to the semiconductor industry. Able to accommodate both

300mm and 200mm wafers simultaneously, the eScan is designed to accelerate 45nm and 32nm technology development and production.

※eScan is a registered trademark of Hermes Microvision, Inc. in the United States Patent and Trademark Office.